

21. A photoresist of claim 19 wherein the polymer comprises pendant acid-labile groups that contain an optionally substituted cycloalkyl group having 3 ring carbons.
22. A photoresist of claim 19 wherein the polymer comprises pendant acid-labile groups that contain an optionally substituted cycloalkyl group having 4 ring carbons.
23. A photoresist of claim 19 wherein the polymer comprises alkyl ester groups.
24. The photoresist of claim 19 wherein the polymer consists essentially of the photoacid generator compound and the polymer.
25. The photoresist of claim 19 wherein the polymer consists essentially of the photoacid generator compound, the polymer and a base component.
26. An article of manufacture comprising a substrate having coated thereon a photoresist composition comprising a photoacid generator compound and a polymer that is substantially free of aromatic groups and that comprises pendant acid-labile groups that contain an optionally substituted cycloalkyl group having 3 or 4 ring carbon atoms, or an optionally substituted alkenyl group.
27. The article of claim 26 wherein the substrate is a microelectronic wafer.
28. The article of claim 27 wherein the polymer comprises alkyl ester groups.

REMARKS

Claims 1-8 and 14-18 have been cancelled without prejudice, and claims 19-28 have been added. No new matter has been added by virtue of those new claims. For instance, support for the new appears e.g. on page 9, lines 15-18; page 15, lines 20-21 and the original